

Please amend the application as follows:

In the Claims:

Please amend the claims as follows:

- B¹
16. (amended) A plastic encapsulated semiconductor device having decreased self and mutual bond wire capacitance, said device including;
- a plurality of substantially parallel, closely-spaced wire bonds connecting pads on an integrated circuit chip to conductive leads,
 - a low dielectric constant sheath surrounding each wire, said sheath covering substantially only said wire and wire connections to said pads on said integrated circuit chip and to said conductive leads, and not covering other portions of said chip and said conductive leads, and
 - a mold compound encasing the chip, sheathed wires, and leads.

REMARKS

Reconsideration of the above-referenced application in view of the following remarks is respectfully requested.

Claims 1-16 and 18 are pending in this application. Claim 16 has been amended to better define the scope of the claimed invention.

The drawings were objected to for not including reference character "15" in Figure 1a. Applicant has included a copy of Figure 1a in which reference number 15 is clearly included. Therefore, Applicant respectfully submits that the drawings are compliant with the relevant regulations.